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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c55a-40-so

PIC16C5X

NOTES:

6.0 MEMORY ORGANIZATION

PIC16C5X memory is organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one or two STATUS Register bits. For devices with a data memory register file of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Selection Register (FSR).

6.1 Program Memory Organization

The PIC16C54, PIC16CR54 and PIC16C55 have a 9-bit Program Counter (PC) capable of addressing a 512 x 12 program memory space (Figure 6-1). The PIC16C56 and PIC16CR56 have a 10-bit Program Counter (PC) capable of addressing a 1K x 12 program memory space (Figure 6-2). The PIC16CR57, PIC16C58 and PIC16CR58 have an 11-bit Program Counter capable of addressing a 2K x 12 program memory space (Figure 6-3). Accessing a location above the physically implemented address will cause a wraparound.

A NOP at the RESET vector location will cause a restart at location 000h. The RESET vector for the PIC16C54, PIC16CR54 and PIC16C55 is at 1FFh. The RESET vector for the PIC16C56 and PIC16CR56 is at 3FFh. The RESET vector for the PIC16C57, PIC16CR57, PIC16CS8, and PIC16CR58 is at 7FFh. See Section 6.5 for additional information using CALL and GOTO instructions.

FIGURE 6-1: PIC16C54/CR54/C55
PROGRAM MEMORY MAP
AND STACK

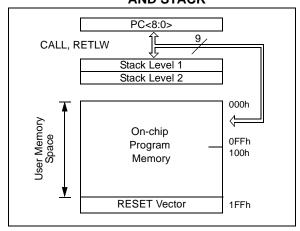


FIGURE 6-2: PIC16C56/CR56
PROGRAM MEMORY MAP
AND STACK

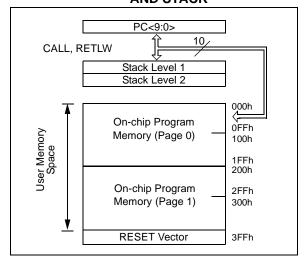
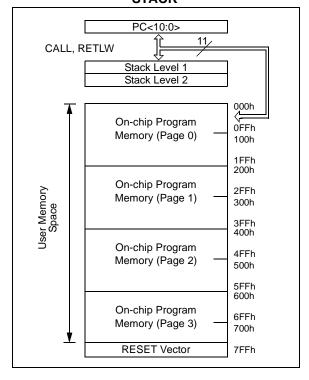


FIGURE 6-3: PIC16C57/CR57/C58/
CR58 PROGRAM
MEMORY MAP AND
STACK



6.5.1 PAGING CONSIDERATIONS – PIC16C56/CR56, PIC16C57/CR57 AND PIC16C58/CR58

If the Program Counter is pointing to the last address of a selected memory page, when it increments it will cause the program to continue in the next higher page. However, the page preselect bits in the STATUS Register will not be updated. Therefore, the next GOTO, CALL or modify PCL instruction will send the program to the page specified by the page preselect bits (PAO or PA<1:0>).

For example, a NOP at location 1FFh (page 0) increments the PC to 200h (page 1). A GOTO xxx at 200h will return the program to address xxh on page 0 (assuming that PA<1:0> are clear).

To prevent this, the page preselect bits must be updated under program control.

6.5.2 EFFECTS OF RESET

The Program Counter is set upon a RESET, which means that the PC addresses the last location in the last page (i.e., the RESET vector).

The STATUS Register page preselect bits are cleared upon a RESET, which means that page 0 is preselected.

Therefore, upon a RESET, a GOTO instruction at the RESET vector location will automatically cause the program to jump to page 0.

6.6 Stack

PIC16C5X devices have a 10-bit or 11-bit wide, two-level hardware push/pop stack.

A CALL instruction will push the current value of stack 1 into stack 2 and then push the current program counter value, incremented by one, into stack level 1. If more than two sequential CALL's are executed, only the most recent two return addresses are stored.

A RETLW instruction will pop the contents of stack level 1 into the program counter and then copy stack level 2 contents into level 1. If more than two sequential RETLW's are executed, the stack will be filled with the address previously stored in level 2. Note that the W Register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.

For the RETLW instruction, the PC is loaded with the Top of Stack (TOS) contents. All of the devices covered in this data sheet have a two-level stack. The stack has the same bit width as the device PC, therefore, paging is not an issue when returning from a subroutine.

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ADDWF	Add	W	and f			
Syntax:	[lab	el]	ADDWF	f,d		
Operands:	0 ≤ 1 d ∈		-			
Operation:	(W)	+ (f)	\rightarrow (dest)			
Status Affected:	C, D)C, Z	<u> </u>			
Encoding:	00	01	11df	ff	ff	
Description:	and is st '1' th	regi orec	contents of ster 'f'. If 'o I in the W esult is sto 'f'.	d' is regi	0 the ster. I	result f 'd' is
Words:	1					
Cycles:	1					
Example:	ADD	WF	TEMP_RE	EG,	0	
Before Instr	uctio	n				
W		=	0x17			
TEMP_I		=	0xC2			
After Instruc	ction					
W		=	0xD9			
TEMP_I	REG	=	0xC2			

ANDWF	AND W with f
Syntax:	[label] ANDWF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(W) .AND. (f) \rightarrow (dest)
Status Affected:	Z
Encoding:	0001 01df ffff
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example:	ANDWF TEMP_REG, 1
Before Instru W TEMP_I After Instruct W TEMP_I	= 0x17 $REG = 0xC2$ $tion$ $= 0x17$

ANDLW	AND literal with W
Syntax:	[label] ANDLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W).AND. (k) \rightarrow (W)
Status Affected:	Z
Encoding:	1110 kkkk kkkk
Description:	The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.
Words:	1
Cycles:	1
Example:	ANDLW H'5F'
Before Instru W = After Instruc W =	0xA3

BCF	Bit Clea	r f							
Syntax:	[label]	BCF f,t)						
Operands:	$0 \le f \le 3^{\prime\prime}$ $0 \le b \le 7$	•							
Operation:	$0 \rightarrow (f < b)$	>)							
Status Affected:	None								
Encoding:	0100	bbbf	ffff						
Description:	Bit 'b' in	register 'f'	is cleared.						
Words:	1								
Cycles:	1								
Example:	BCF	FLAG_RE	EG, 7						
Before Instru		0.07							
FLAG_R After Instruct		0xC7							
FLAG_R		0x47							

TABLE 11-1: DEVELOPMENT TOOLS FROM MICROCHIP

MPLAB® Integrated	> >	> > > > > > >	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	> > > > >	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	S S S S S S	, , , , , , , , , , , , , , , , , , ,		
MPLAB® C17 C Compiler MPLAB® C18 C Compiler				S S S S S	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \				
MPLAB® C18 C Compiler		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		S S S S			
MPASM™ Assembler/ MPLINK™ Object Linker ✓		>> > > >	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	> > > >	> > > >	S S S S			
MPLAB® ICE In-Circuit Emulator	> > > >	> > >	> > > >	\$ \$	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	, , ,	\ \ \ \ \ \		
ICEPIC™ In-Circuit Emulator	> > >	> > >	\ \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	\ \ \ \ \ \	\ \ \ \ \ \ \	\	, ,		
MPLAB® ICD In-Circuit Debugger PICSTART® Plus Entry Level Development Programmer PRO MATE® II Universal Device Programmer PICDEM™ 1 Demonstration Board PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 14A Demonstration Board PICDEM™ 14A Demonstration PICDEM™ 15	> >	· · ·	> >	\ \ \ \	> >	, ,	> >		
PICSTART® Plus Entry Level Development Programmer PRO MATE® II Universal Device Programmer PICDEM™ 1 Demonstration Board PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 4A Demonstration PICDEM™ 4A Demonstration PICDEM™ 4A Demonstration	> >	> >	> >	> >	> >	, ,	>		
PRO MATE® II Universal Device Programmer PICDEM™ 1 Demonstration Board PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 4A Demonstration Board PICDEM™ 4A Demonstration Board PICDEM™ 4A Demonstration	>	>	>	`	>	``			
W TM 1 Demonstration W TM 2 Demonstration W TM 3 Demonstration					_		`	<u>`</u>	
PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 14A Demonstration	+			>					
PICDEM™ 3 Demonstration Board PICDEM™ 14A Demonstration Board						>	`		
PICDEM™ 14A Demonstration Board			>						
PICDEM™ 17 Demonstration Board					>				
								>	
								>	
microID™ Programmer's Kit									>
5 125 kHz microID™ Developer's Kit									>
125 kHz Anticollision microlD TM Developer's Kit									>
13.56 MHz Anticollision microlD™ Developer's Kit									>
MCP2510 CAN Developer's Kit									

12.4 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial) PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

DC CH	ARACTE	RISTICS	Standard O Operating Te		ire 0°C	≤ TA ≤ +	s otherwise specified) -70°C for commercial -85°C for industrial
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1 (Schmitt Trigger)	Vss Vss Vss Vss Vss	_ _ _ _	0.2 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.3 VDD	V V V V	Pin at hi-impedance PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP
D040	ViH	Input High Voltage I/O ports I/O ports I/O ports MCLR (Schmitt Trigger) TOCKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1 (Schmitt Trigger)	0.45 VDD 2.0 0.36 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.7 VDD		VDD VDD VDD VDD VDD VDD	V V V V V	For all VDD ⁽⁴⁾ 4.0V < VDD ≤ 5.5V ⁽⁴⁾ VDD > 5.5V PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	_	_	V	
D060	IIL	Input Leakage Current ^(1,2) I/O ports MCLR MCLR TOCKI OSC1	-1 -5 -3 -3	0.5 — 0.5 0.5 0.5	+1 +5 +3 +3	μΑ μΑ μΑ μΑ μΑ	For Vdd \leq 5.5V: VSS \leq VPIN \leq VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS \leq VPIN \leq VDD VSS \leq VPIN \leq VDD, PIC16C5X-XT, 10, HS, LP
D080	Vol	Output Low Voltage I/O ports OSC2/CLKOUT	_	_	0.6 0.6	V V	IOL = 8.7 mA, VDD = 4.5V IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC
D090	Voн	Output High Voltage ⁽²⁾ I/O ports OSC2/CLKOUT	VDD - 0.7 VDD - 0.7	_ _	_ _	V V	IOH = -5.4 mA, VDD = 4.5V IOH = -1.0 mA, VDD = 4.5V, PIC16C5X-RC

^{*} These parameters are characterized but not tested.

- 2: Negative current is defined as coming out of the pin.
- **3:** For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.
- 4: The user may use the better of the two specifications.

[†] Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

12.7 Timing Diagrams and Specifications

FIGURE 12-2: EXTERNAL CLOCK TIMING - PIC16C54/55/56/57

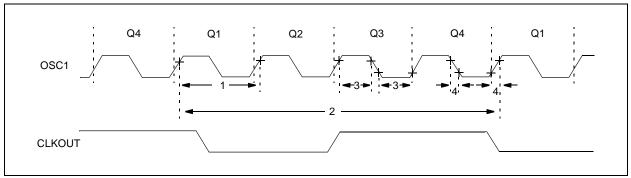


TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Chara	cteristics	-40)°C ≤])°C ≤]	nless oth 「A ≤ +70° 「A ≤ +85° 「A ≤ +125	C for con	nmercia ustrial	•
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency ⁽¹⁾	DC	_	4.0	MHz	XT osc mode
			DC	_	10	MHz	10 MHz mode
			DC	_	20	MHz	HS osc mode (Comm/Ind)
			DC	_	16	MHz	HS osc mode (Ext)
			DC	_	40	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	_	4.0	MHz	RC osc mode
			0.1	_	4.0	MHz	XT osc mode
			4.0	_	10	MHz	10 MHz mode
			4.0	_	20	MHz	HS osc mode (Comm/Ind)
			4.0	_	16	MHz	HS osc mode (Ext)
			DC	_	40	kHz	LP osc mode

^{*} These parameters are characterized but not tested.

- Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

 When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.
 - 2: Instruction cycle period (Tcy) equals four times the input oscillator time base period.

[†] Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

	R54A-04 R54A-04I ercial, Indus	trial)		ard Oper ting Tem	_	9 0°	s (unless otherwise specified) $C \le TA \le +70^{\circ}C$ for commercial $C \le TA \le +85^{\circ}C$ for industrial
PIC16CR	54A-04, 10 54A-04I, 10 ercial, Indus), 1, 20l		ard Oper ting Temp	_	0°	s (unless otherwise specified) $C \le TA \le +70^{\circ}C$ for commercial $C \le TA \le +85^{\circ}C$ for industrial
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
	IPD	Power-down Current ⁽²⁾					
D006		PIC16LCR54A-Commercial	_ _ _ _	1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled
D006A		PIC16CR54A-Commercial	_ _ _ _	1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled
D007		PIC16LCR54A-Industrial		1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μΑ μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 4.0V, WDT enabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled
D007A		PIC16CR54A-Industrial	_ _ _ _	1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μΑ μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 4.0V, WDT enabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in $k\Omega$.

13.6 Timing Diagrams and Specifications

FIGURE 13-2: EXTERNAL CLOCK TIMING - PIC16CR54A

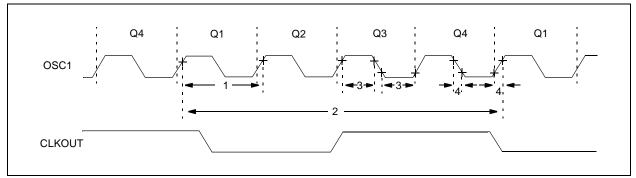


TABLE 13-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A

AC Chara	cteristics	Operating Temperature 0° -40°	${}^{C}C \leq TA$ ${}^{C}C \leq TA$. ≤ +70°C . ≤ +85°C :	for com	mercial strial	•
Param No.	Symbol	$-40^{\circ}\text{C} \leq \text{TA} \leq +85^{\circ}\text{C for industrial} \\ -40^{\circ}\text{C} \leq \text{TA} \leq +125^{\circ}\text{C for extended}$ ol Characteristic Min Typ† Max Units Conditions $E = \text{External CLKIN Frequency}^{(1)} DC - 4.0 \text{MHz} \text{XT osc mode} \\ DC - 4.0 \text{MHz} \text{HS osc mode (04)} \\ DC - 10 \text{MHz} \text{HS osc mode (10)} \\ DC - 20 \text{MHz} \text{HS osc mode (20)} \\ DC - 200 \text{kHz} \text{LP osc mode}$ $Oscillator Frequency^{(1)} DC - 4.0 \text{MHz} \text{RC osc mode} \\ 0.1 - 4.0 \text{MHz} \text{XT osc mode} \\ 4.0 - 4.0 \text{MHz} \text{HS osc mode} (04)$					
	Fosc	External CLKIN Frequency ⁽¹⁾	DC	_	4.0	MHz	XT osc mode
			DC	_	4.0	MHz	HS osc mode (04)
			DC	_	10	MHz	HS osc mode (10)
			DC	_	20	MHz	HS osc mode (20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	_	4.0	MHz	RC osc mode
			0.1	_	4.0	MHz	XT osc mode
			4.0	_	4.0	MHz	HS osc mode (04)
			4.0	_	10	MHz	HS osc mode (10)
			4.0	_	20	MHz	HS osc mode (20)
			5.0	_	200	kHz	LP osc mode

^{*} These parameters are characterized but not tested.

- Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

 When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.
 - 2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

[†] Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial)
PIC16C54A-04I, 10I, 20I (Industrial)
PIC16LC54A-04 (Commercial)
PIC16LC54A-04I (Industrial)

PIC16LC PIC16LC (Comm		ustrial)		ard Ope ting Tem		ire	tions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $40^{\circ}C \le TA \le +85^{\circ}C$ for industrial
PIC16C5	64A-04, 10 64A-04I, 1 ercial, Ind	0I, 20I		ard Ope ting Tem		ire	tions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $40^{\circ}C \le TA \le +85^{\circ}C$ for industrial
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
	VDD	Supply Voltage					
D001		PIC16LC54A	3.0 2.5	_	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.0 4.5		6.25 5.5	V V	RC, XT and LP modes HS mode
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	1	1.5*	_	>	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset		Vss	_	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	_	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	Supply Current ⁽²⁾					
D005		PIC16LC5X	_	0.5	2.5	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
				11	27	μΑ	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial
				11	35	μΑ	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial
D005A		PIC16C5X		1.8	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
			_	2.4	8.0	mΑ	FOSC = 10 MHz, VDD = 5.5V, HS mode
			_	4.5	16	mΑ	FOSC = 20 MHz, VDD = 5.5V, HS mode
			_	14	29	μΑ	Fosc = 32 kHz, VDD = 3.0V,
			_	17	37	μΑ	WDT disabled, LP mode, Commercial Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

- * These parameters are characterized but not tested.
- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in $k\Omega$.

FIGURE 15-5: TIMERO CLOCK TIMINGS - PIC16C54A

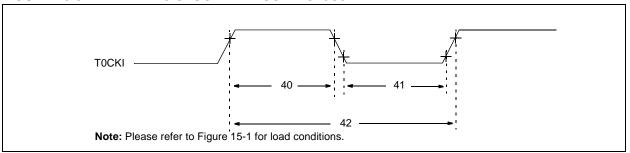


TABLE 15-4: TIMERO CLOCK REQUIREMENTS - PIC16C54A

TABLE 15-4:	HIMERO CLOC	K REQUIREMENTS	- PIC16C54A				
		Standard Operating	Conditions (ur	nless o	therw	ise spe	cified)
		Operating Temperatu	ure 0°C ≤	T A ≤ + 7	70°C fo	or comn	nercial
AC Cha	racteristics		-40°C ≤	T A ≤ + 8	5°C fo	or indus	trial
			– 20°C ≤	T A ≤ + 8	S5°C fo	or indus	trial - PIC16LV54A-02I
			-40°C ≤	TA ≤ +1	25°C	for exte	nded

Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	_	_	ns	
		- With Prescaler	10*	_	_	ns	
41	Tt0L	T0CKI Low Pulse Width					
		- No Prescaler	0.5 Tcy + 20*	_	_	ns	
		- With Prescaler	10*	_	_	ns	
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N	_	1		Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

16.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

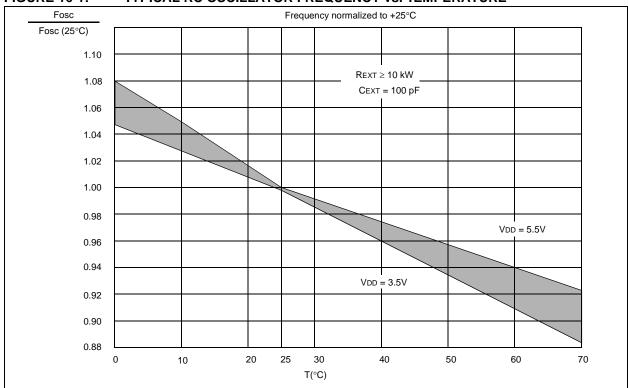


FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

TABLE 16-1: RC OSCILLATOR FREQUENCIES

Сехт	REXT	Average Fosc @ 5 V, 25°C				
20 pF	3.3K	5 MHz	± 27%			
	5K	3.8 MHz	± 21%			
	10K	2.2 MHz	± 21%			
	100K	262 kHz	± 31%			
100 pF	3.3K	1.6 MHz	± 13%			
	5K	1.2 MHz	± 13%			
	10K	684 kHz	± 18%			
	100K	71 kHz	± 25%			
300 pF	3.3K	660 kHz	± 10%			
	5.0K	484 kHz	± 14%			
	10K	267 kHz	± 15%			
	100K	29 kHz	± 19%			

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ± 3 standard deviation from average value for VDD = 5V.

FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 20 PF, 25°C

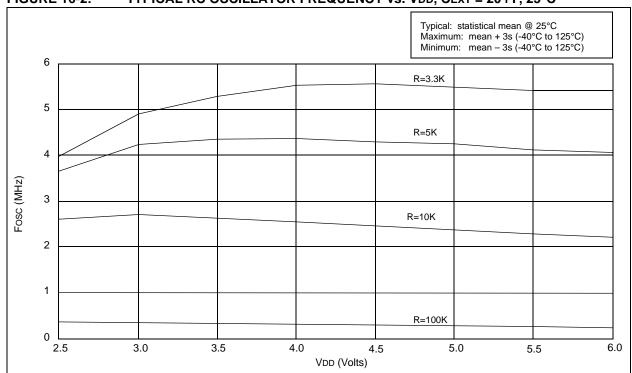
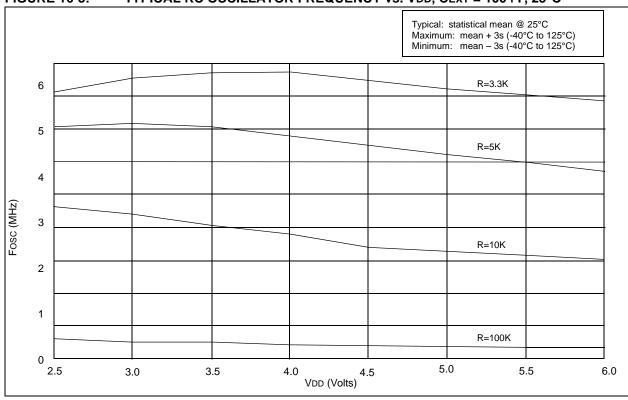
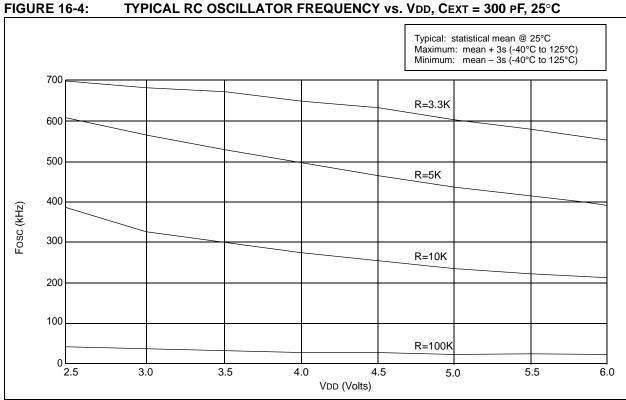


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 100 PF, 25°C





17.5 Timing Diagrams and Specifications

FIGURE 17-6: EXTERNAL CLOCK TIMING - PIC16C5X, PIC16CR5X

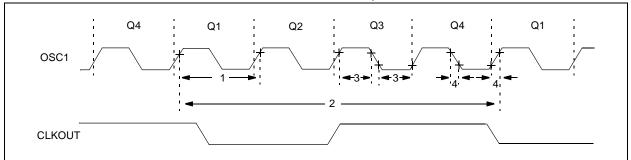


TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

	Standard Operating Co	nditions (unless otherwise specified)	
AC Characteristics	Operating Temperature	$0^{\circ}C \le TA \le +70^{\circ}C$ for commercial	
AC Characteristics		-40°C ≤ TA ≤ +85°C for industrial	
		-40 °C \leq TA \leq +125°C for extended	

Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency(1)	DC		4.0	MHz	XT osc mode
			DC	_	4.0	MHz	HS osc mode (04)
			DC	_	20	MHz	HS osc mode (20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	_	4.0	MHz	RC osc mode
			0.45	_	4.0	MHz	XT osc mode
			4.0	_	4.0	MHz	HS osc mode (04)
			4.0	_	20	MHz	HS osc mode (20)
			5.0	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period ⁽¹⁾	250	_	_	ns	XT osc mode
			250	_		ns	HS osc mode (04)
			50	_		ns	HS osc mode (20)
			5.0	_		μS	LP osc mode
		Oscillator Period ⁽¹⁾	250	_	_	ns	RC osc mode
			250	_	2,200	ns	XT osc mode
			250	_	250	ns	HS osc mode (04)
			50	_	250	ns	HS osc mode (20)
			5.0	_	200	μS	LP osc mode

^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

^{2:} Instruction cycle period (TCY) equals four times the input oscillator time base period.

TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for extended						
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions	
2	Tcy	Instruction Cycle Time ⁽²⁾	_	4/Fosc	_	_		
3	TosL, TosH	Clock in (OSC1) Low or High	50*	_	_	ns	XT oscillator	
		Time	20*	_	_	ns	HS oscillator	
			2.0*	_		μS	LP oscillator	
4	TosR, TosF	Clock in (OSC1) Rise or Fall	_	_	25*	ns	XT oscillator	
		Time	_	_	25*	ns	HS oscillator	
					50*	ne	I P oscillator	

^{*} These parameters are characterized but not tested.

- Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

 When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.
 - 2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

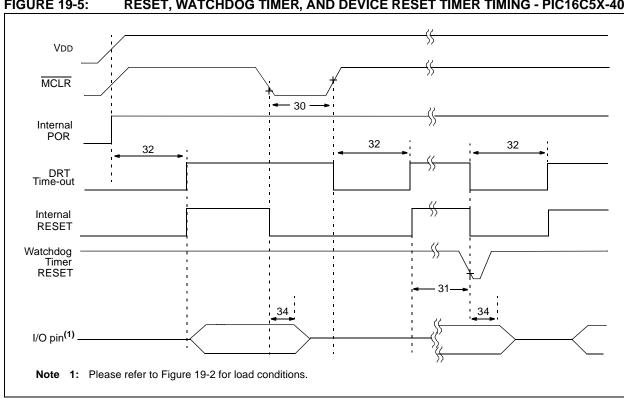


FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

AC Characteristics		Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial) Operating Voltage VDD range is described in Section 19.1.						
Param No. Symbol		Characteristic	Min Typ† Max Units		Units	Conditions		
30	TmcL	MCLR Pulse Width (low)	1000*	_	_	ns	VDD = 5.0V	
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)	
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)	
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns		

These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 19-6: TIMERO CLOCK TIMINGS - PIC16C5X-40

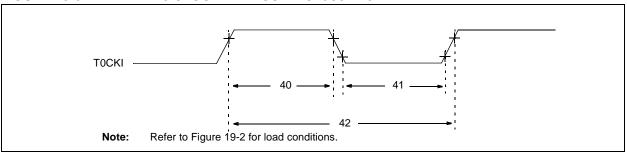


TABLE 19-4: TIMERO CLOCK REQUIREMENTS PIC16C5X-40

A	AC Charac	TERISTICS	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Max Units	Conditions		
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 Tcy + 20*	_		ns			
		- With Prescaler	10*		—	ns			
41	TtOL	T0CKI Low Pulse Width - No Prescaler	0.5 Tcy + 20*	_	_	ns			
		- With Prescaler	10*		—	ns			
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N	_	_	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)		

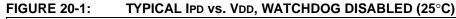
^{*} These parameters are characterized but not tested.

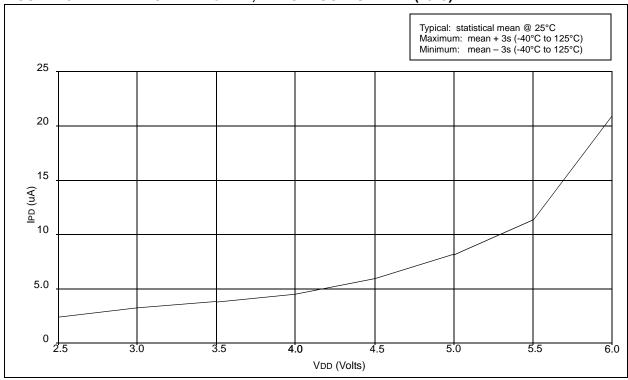
[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

20.0 DEVICE CHARACTERIZATION - PIC16LC54C 40MHz

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"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.





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